

QSS-050-01-F-D-A

QSS-075-01-F-D-A

QSS-025-01-L-D-A

(0.635 mm) .025"

QSS SERIES

HIGH-SPEED GROUND PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com/QSS

Insulator Material:
Liquid Crystal Polymer
Contact Material:
Phosphor Bronze

Plating:

Au or Sn over
50 μ " (1.27 μ m) Ni

Current Rating:
Contact: 1.8 A per pin
(2 pins powered)

Ground Plane:
23.1 A per ground plane
(1 ground plane powered)

Operating Temp:
-55 °C to +125 °C

Voltage Rating:
285 VAC

Max Cycles:
100

RoHS Compliant:
Yes

Board Mates:
QTS

Cable Mates:
SQCD

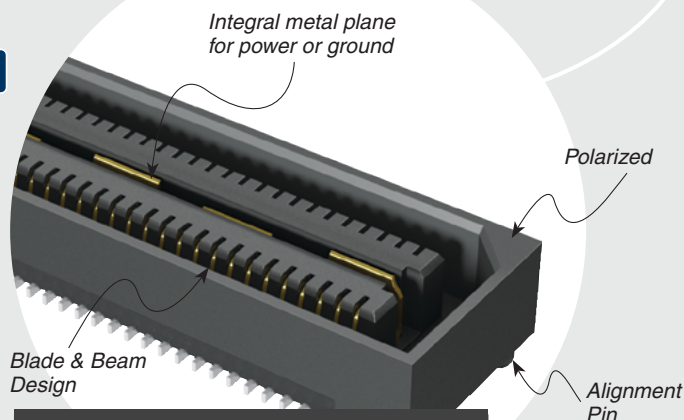
Standoffs:
SO



POWER/SIGNAL APPLICATION



Compatible with
UMPT/UMPS for flexible
two-piece power/signal solutions



HIGH-SPEED CHANNEL PERFORMANCE

QSS/QTS @ 5 mm Mated Stack Height

Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com
or contact SIG@samtec.com

25
Gbps

PROCESSING

Lead-Free Solderable:
Yes

SMT Lead Coplanarity:
(0.10 mm) .004" max (025-050)
(0.15 mm) .006" max (075)*
*(.004" stencil solution
may be available; contact
IPG@samtec.com)

Board Stacking:
For applications requiring more
than two connectors per board
contact ipg@samtec.com

RECOGNITIONS

For complete scope of
recognitions see
www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- 11 mm & 16 mm stack height
- 30 μ " (0.76 μ m) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 100 & 125 positions per row
- Edge Mount
- -LS2 Locking screw hole for QTS-RA-LS2

Note:
Some lengths, styles and
options are non-standard,
non-returnable.

QSS — NO. OF POSITIONS PER ROW — 01 — PLATING OPTION — D — A — OTHER OPTION

—025, —050, —075
(50 total positions per bank)

—F

= Gold Flash on Signal Pins and
Ground Plane, Matte Tin on tails

—L

= 10 μ " (0.25 μ m) Gold on Signal Pins
and Ground Plane, Matte Tin on tails

—C*

= Electro-Polished Selective
50 μ " (1.27 μ m) min Au over
150 μ " (3.81 μ m) Ni on Signal Pins
in contact area, 10 μ " (0.25 μ m) min
Au over 50 μ " (1.27 μ m) Ni on
Ground Plane in contact area,
Matte Tin over 50 μ " (1.27 μ m) min
Ni on all solder tails

—GP

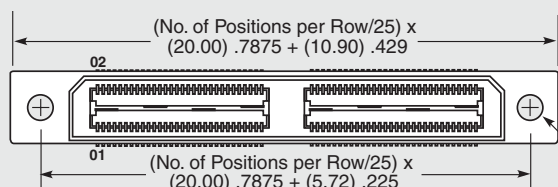
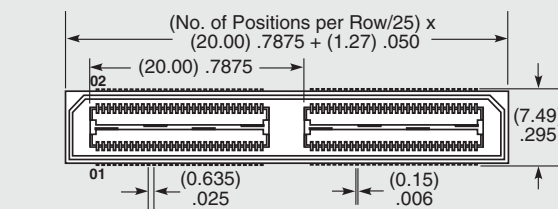
= Guide Holes
for mating
with QTS-RA

—K

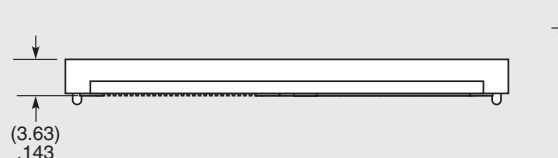
= (8.25 mm)
.325" DIA
Polyimide Film
Pick &
Place Pad

—TR

= Tape & Reel



*Note: —C Plating passes
10 year MFG testing



QTS LEAD STYLE	MATED HEIGHT WITH QSS
—01	(5.00) .197
—02	(8.00) .315

Processing conditions will affect
mated height. See SO Series for
board space tolerances

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.
Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.